

MAZE062D

Silicon planar type

For surge absorption circuit

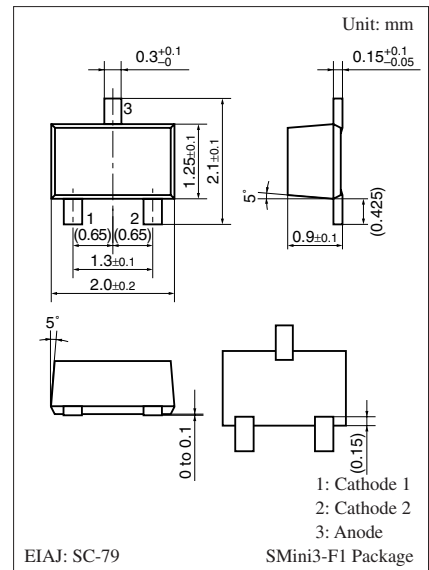
■ Features

- Low joint capacity zener diode

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

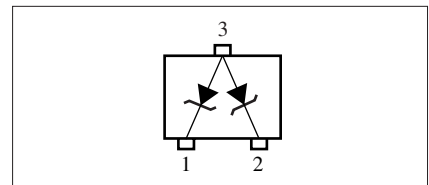
Parameter	Symbol	Rating	Unit
Repetitive peak forward current	I_{FRM}	200	mA
Power dissipation *	P_D	150	mW
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

Note) *: $P_D = 200$ mW achieved with a printed circuit board.



Marking Symbol: 6.2C

Internal connection



■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 10$ mA		0.9	1.0	V
Zener voltage *	V_Z	$I_Z = 5$ mA	5.9		6.5	V
Zener rise operating resistance	R_{ZK}	$I_Z = 0.5$ mA			100	Ω
Zener operating resistance	R_Z	$I_Z = 5$ mA			30	Ω
Reverse current	I_R	$V_R = 5.5$ V			3	μA
Terminal capacitance	C_t	$V_R = 0$ V, $f = 1$ MHz		8		pF

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 5 MHz.

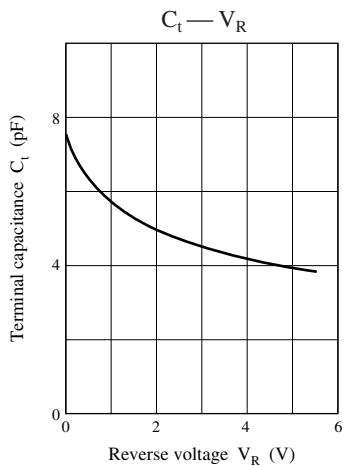
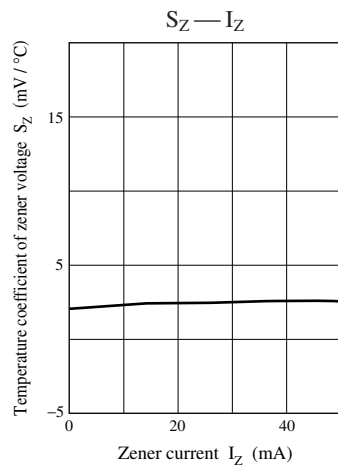
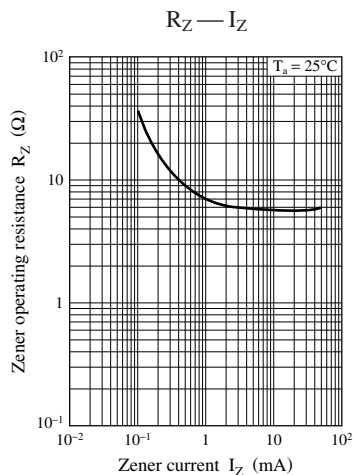
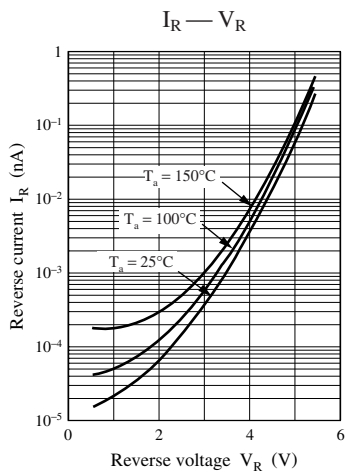
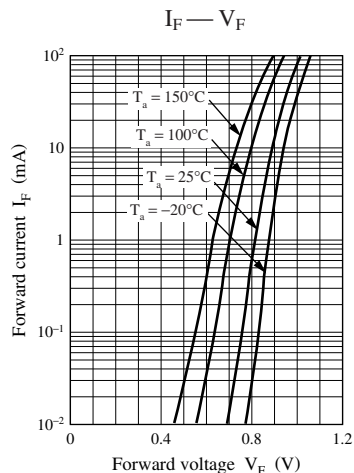
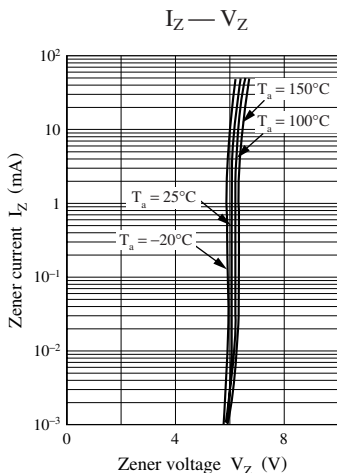
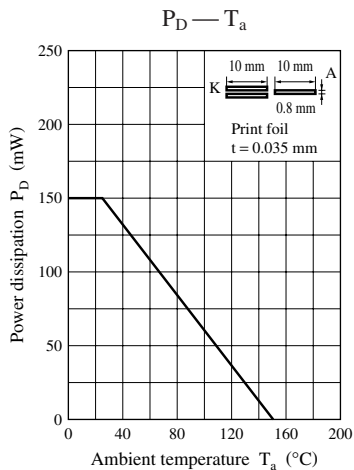
3. Electrostatic breakdown voltage: ± 15 kV

Test method: IEC-801 (C = 150 pF, R = 330 Ω , Contact discharge: 10 times)

Test unit: ESS-200AX

4. *: The V_Z value is for the temperature of 25°C . In other cases, carry out the temperature compensation.

Guaranteed at 20 ms after power application.



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